

HiPerDynFRED

 V_{RRM} 1200 V 25 A

15 ns

High Performance Dynamic Fast Recovery Diode Extreme Low Loss and Soft Recovery Parallel legs with series connected dice

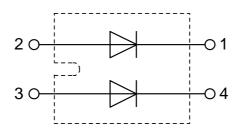
Part number

DSEP2x25-12C



Backside: isolated

F1 E72873



Features / Advantages:

- Planar passivated chips
- Very low leakage current
- · Very short recovery time
- Improved thermal behaviour
- Very low Irm-values
- Very soft recovery behaviour
- Soft reverse recovery for low EMI/RFI
- Low Irm reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- · Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate: Copper
- internally DCB isolated Advanced power cycling

Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

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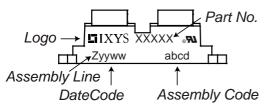


Fast Diode					Ratings		
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V _{RSM}	max. non-repetitive reverse blocki	ng voltage	$T_{VJ} = 25^{\circ}C$			1200	V
V _{RRM}	max. repetitive reverse blocking v	oltage	$T_{VJ} = 25^{\circ}C$			1200	V
I _R	reverse current, drain current	V _R = 1200 V	$T_{VJ} = 25^{\circ}C$			250	μΑ
		$V_R = 1200 \text{ V}$	$T_{VJ} = 150$ °C			2	mΑ
V _F	forward voltage drop	I _F = 25 A	$T_{VJ} = 25^{\circ}C$			4.71	V
		$I_F = 50 A$				5.92	V
		I _F = 25 A	T _{VJ} = 150°C			2.95	V
		$I_F = 50 A$				4.01	V
I _{FAV}	average forward current	T _c = 90°C	T _{VJ} = 150°C			25	Α
		rectangular d = 0.5					1 1 1 1
V _{F0}	threshold voltage	and a decide Common by	$T_{VJ} = 150$ °C			1.95	V
\mathbf{r}_{F}	slope resistance	oss calculation only				40	mΩ
R _{thJC}	thermal resistance junction to cas	е				0.6	K/W
R _{thCH}	thermal resistance case to heatsin	nk			0.10		K/W
P _{tot}	total power dissipation		$T_C = 25^{\circ}C$			210	W
I _{FSM}	max. forward surge current	$t = 10 \text{ ms}$; (50 Hz), sine; $V_R = 0 \text{ V}$	$T_{VJ} = 45^{\circ}C$			250	Α
C	junction capacitance	$V_R = 400 \text{V}$ f = 1 MHz	$T_{VJ} = 25^{\circ}C$		18		pF
I _{RM}	max. reverse recovery current	<u>, </u>	T _{vJ} = 25 °C		5.5		Α
		$I_F = 30 \text{ A}; V_R = 600 \text{ V}$	$T_{VJ} = 100 ^{\circ}C$		12.5		Α
t _{rr}	reverse recovery time	$\begin{cases} I_F = 30 \text{ A; } V_R = 600 \text{ V} \\ -di_F /dt = 600 \text{ A/} \mu \text{s} \end{cases}$	$T_{VJ} = 25 ^{\circ}\text{C}$		15		ns
	-)	$T_{VJ} = 100 ^{\circ}C$		70		ns



Package SOT-227B (minibloc)			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I _{RMS}	RMS current	per terminal					100	Α
T _{VJ}	virtual junction temperature				-40		150	°C
Top	operation temperature				-40		125	°C
T _{stg}	storage temperature			-40		150	°C	
Weight						30		g
M _D	mounting torque		1.1		1.5	Nm		
$\mathbf{M}_{_{\mathbf{T}}}$	terminal torque		1.1		1.5	Nm		
d _{Spp/App}	creepage distance on surface striking distance through air		terminal to terminal	10.5	3.2			mm
d _{Spb/Apb}	creepage distance on sunat	ce striking distance through an	terminal to backside 8.6		6.8			mm
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz, RMS; IsoL ≤ 1 mA		3000			V
.002		t = 1 minute			2500			V

Product Marking

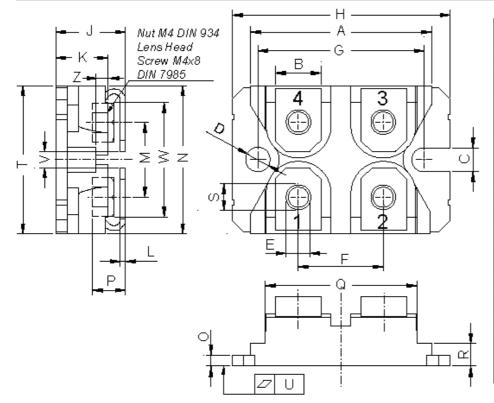


Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	DSEP2x25-12C	DSEP2x25-12C	Tube	10	482021

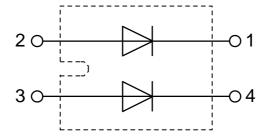
Equivalent Circuits for Simulation			* on die level	$T_{VJ} = 150 ^{\circ}\text{C}$
I(V ₀	R_0	Fast Diode		
V _{0 max}	threshold voltage	1.95		V
R_{0max}	slope resistance *	36		$m\Omega$



Outlines SOT-227B (minibloc)



D:	Millir	Millimeter		hes
Dim.	min	max	min	max
Α	31.50	31.88	1.240	1.255
В	7.80	8.20	0.307	0.323
С	4.09	4.29	0.161	0.169
D	4.09	4.29	0.161	0.169
Е	4.09	4.29	0.161	0.169
F	14.91	15.11	0.587	0.595
G	30.12	30.30	1.186	1.193
Н	37.80	38.23	1.488	1.505
J	11.68	12.22	0.460	0.481
K	8.92	9.60	0.351	0.378
L	0.74	0.84	0.029	0.033
M	12.50	13.10	0.492	0.516
N	25.15	25.42	0.990	1.001
0	1.95	2.13	0.077	0.084
Р	4.95	6.20	0.195	0.244
Q	26.54	26.90	1.045	1.059
R	3.94	4.42	0.155	0.167
S	4.55	4.85	0.179	0.191
Т	24.59	25.25	0.968	0.994
U	-0.05	0.10	-0.002	0.004
V	3.20	5.50	0.126	0.217
W	19.81	21.08	0.780	0.830
Ζ	2.50	2.70	0.098	0.106





Fast Diode

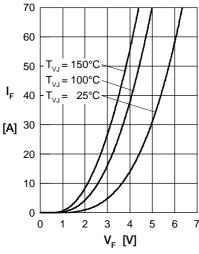


Fig. 1 Forward current I_F versus V_F

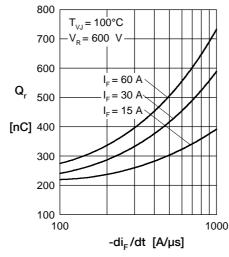


Fig. 2 Typ. reverse recov. charge Q_r versus $-di_F/dt$

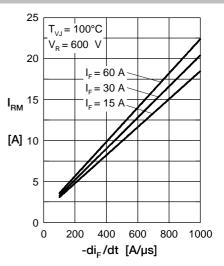


Fig. 3 Typ. peak reverse current $I_{\rm RM}$ versus $-{\rm di_F}/{\rm dt}$

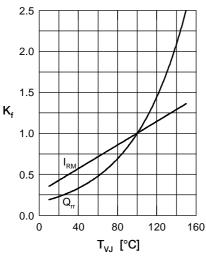


Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus T_{VJ}

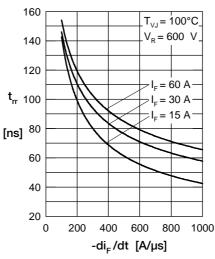


Fig. 5 Typ. recovery time t_{rr} versus $-di_{F}/dt$

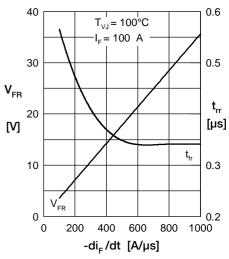


Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_{F}/dt

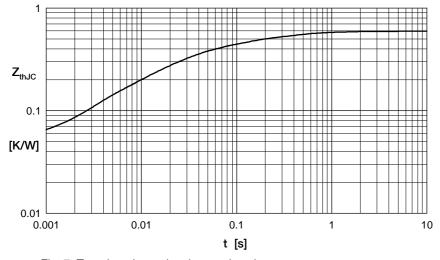


Fig. 7 Transient thermal resistance junction to case

Constants for $Z_{\rm thJC}$ calculation:

i	R_{thi} (K/W)	t _i (s)
1	0.037	0.00024
2	0.07	0.0036
3	0.246	0.0235
4	0.176	0.142
5	0.07	0.7

Mouser Electronics

Authorized Distributor

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IXYS:

DSEP2x25-12C